



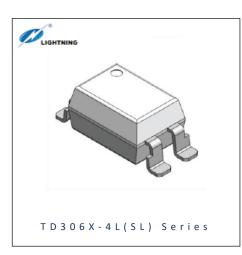
PRODUCT DATASHEET



- DC Input Photo Coupler
- Zero-Cross TRIAC

TD306X-4L(SL)(T1)-GV





APPLICATIONS:

- Solenoid/valve controls •
- Lighting controls
- Motor controls •
- **Temperature controls** .
- Static AC power switches
- Solid state relays •
- Interfacing microprocessors to 115 • to 240VAC peripherals

TD306X-4L(SL) Series

DESCRIPTION:



The TDTD306X-4L(SL) series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon zero-cross photo TRIAC in a plastic DIP4 package with SMD4 Low Profile lead forming option.

With the robust coplanar double mold structure, TD306X-4L(SL) series provide the most stable isolation feature.

FEATURES:

- High isolation 5000Vrms
- DC input with zero-cross photo TRIAC output
- Operating temperature range -40°C to +100°C
- **REACH & RoHS compliance; Halogen free**
- MSL class 1
- **Regulatory Approvals:**
 - UL UL1577 0
 - VDE EN60747-5-5 (VDE0884-5) 0
 - 0 CQC - GB4943.1, GB8898

• **IR IR**

cUL - CSA Component Acceptance Service Notice 5A 0

Packing: T1/T2: 1500pcs/reel; T3/T4: 1000pcs/reel CQC Partner with: WLIGHTNING



Naming Information:

TD306 X - 4L (SL) (T1) - G V				
TD306	Part Number			
×	Selection: LED Trigger Current (X=1~3)			
4L	DIP4 Based Package			
SL	Lead Form Option: SMD4 Low Profile			
T1	Selection: Tape and Reel Option (T1(default)/T2/T3/T4)			
G	Green Option			
V	VDE Option			

Ordering Information:

TD306 <u>X</u> -4L(SL)(T1)-GV						
	<u>X</u> = Selection: LED Trigger Current (X=1~3)					
Part Number	Symbol	Values		Unit	Test Condition	
	Symbol	Min.	Тур.	Max.	onnt	rest condition
TD3061-4L(SL)(T1)-GV				15		100m 1
TD3062-4L(SL)(T1)-GV	I _{FT}			10	mA	I™=100mA Terminal
TD3063-4L(SL)(T1)-GV				5		Voltage=3V

Version No.	Original Release Date
Rev: A00	05/09/2024



Image: PIN Definition 1 Anode 2 Cathode 3 Terminal 4 Terminal

Schematic Diagram:

Marking Information:

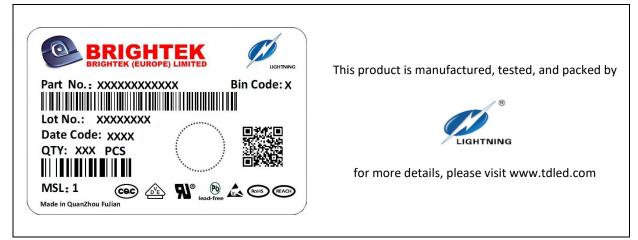
TD

30XX

VYAWW

Marking Definition		
TD	Manufacturer Code	
306X	Part Number & Rank	
v	VDE Applicable	
Y	Fiscal Year	
А	Manufacturing Code	
ww	Work Week	

Labelling Information:





Absolute Maximum Ratings:

Parameter	Symbol	Ratings	Unit			
INPUT						
Forward Current	IF	60	mA			
Reverse Voltage	VR	6	V			
Junction Temperature	Tj	125	°C			
Input Power Dissipation	Pı	100	mW			
	OUTPUT					
Off-State Output Terminal Voltage	V _{DRM}	600	V			
Peak Repetitive Surge Current PW=100μs, 120pps	Ітѕм	1	А			
On-State RMS Current	It(rms)	100	mA			
Junction Temperature	Tj	125	°C			
Output Power Dissipation	Po	300	mW			
COMMON						
Total Power Dissipation	P _{tot}	400	mW			
Isolation Voltage	Viso	5000 ^{*1}	Vrms			
Operating Temperature	Topr	-40~+100	°C			
Storage Temperature	T _{stg}	-55~+125	°C			
Soldering Temperature	T _{sol}	260 *2	°C			

*1. AC for 1 minute, R.H.=40~60%.

*2. For 10 seconds max.



ELECTRICAL CHARACTERISTICS:

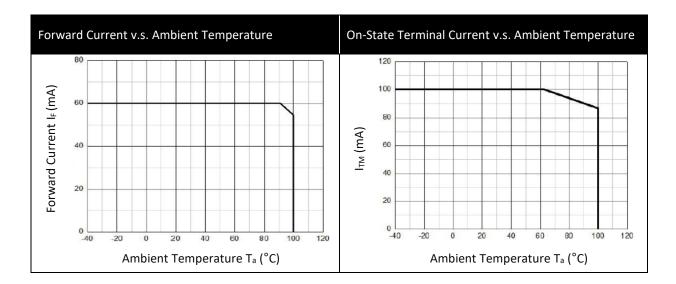
Electrical Op	otical Characteristics	at T _a =25°C:
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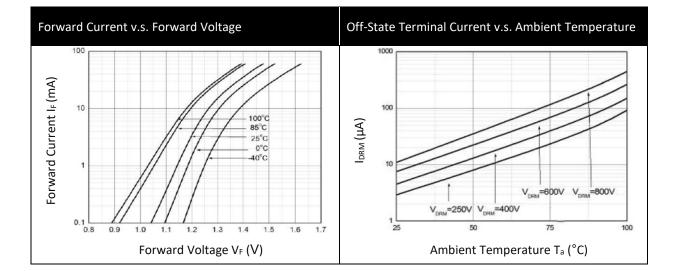
Paramete	er	Symbol	Min.	Values Typ.	Max.	Unit	Test Condition
INPUT							
Forward Voltage		V _F		1.24	1.4	v	I _F =10mA
Reverse Current		I _R			10	μΑ	V _R =6V
Input Capacitance		CIN		8.5	250	pF	V=0, f=1kHz
		1	OUTPL	JT	1	1	
Peak Off-State Curre Either Direction	nt	Idrm			500 ^{*1}	nA	V_{DRM} =Rated V_{DRM} I _F =0
Peak Off-State Voltag	ge	V _{TM}		1.59	2.5	v	I _{TM} =100mA
Critical Rate of Rise of Voltage	of Off-State	dV/dt	1000			V/µs	V _{PEAK} =400V I _F =0
		TRAN	NSFER CHAR	ACTERISTICS			
	TD3061-4L				15		I™=100mA Terminal
LED Trigger Current	TD3062-4L	IFT			10	mA	
	TD3063-4L				5		Voltage=3V
Holding Current		Ін		237		μA	
Isolation Resistance		R _{ISO}	10^12	10^14		Ω	DC=500V, 40~60% R.H.
Floating Capacitance		Сю		0.4	1	pF	V=0, f=1MHz
ZERO-CROSSING CHARACTERISTICS							
Inhibit Voltage		VINH			20	V	IF=Rated IFT
Leakage in Inhibited	State	I _{DRM2}			500	μΑ	IF=Rated IFT VDRM=Rated VDRM

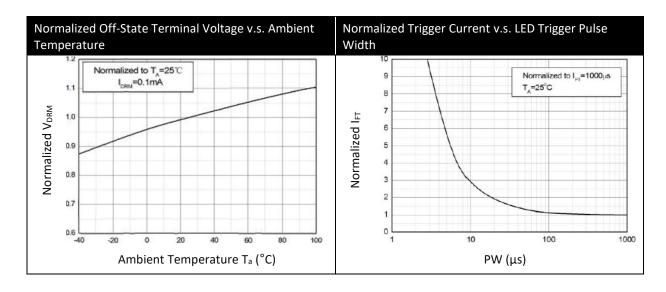
*1. Test voltage must be applied within dV/dt rating.



CHARACTERISTIC CURVES:

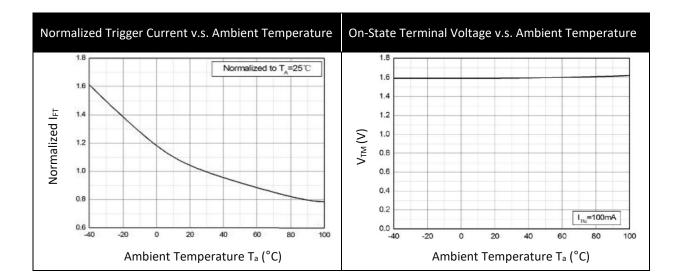


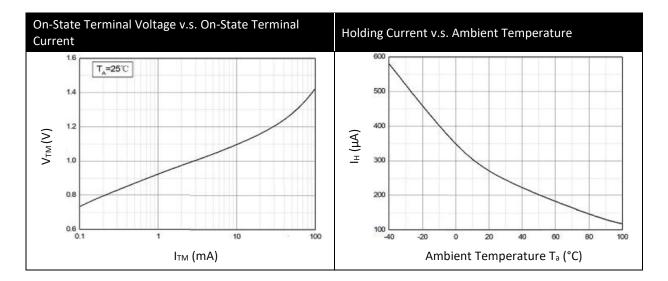


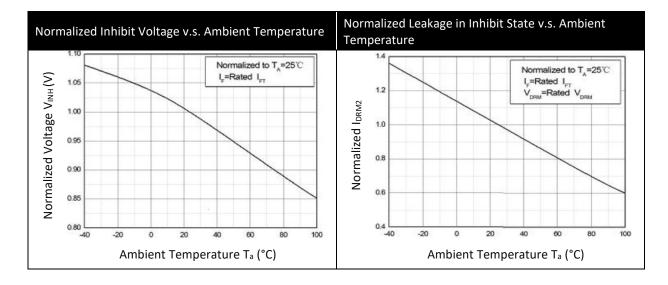




CHARACTERISTIC CURVES:

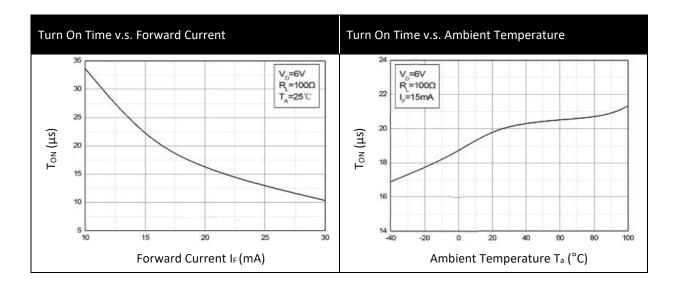






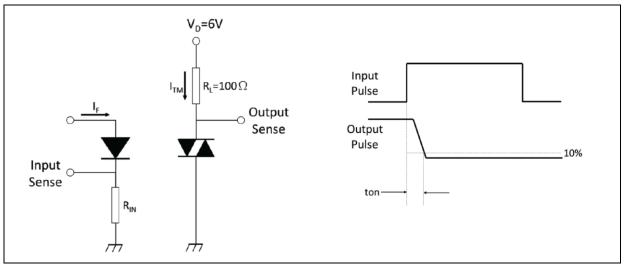


CHARACTERISTIC CURVES:



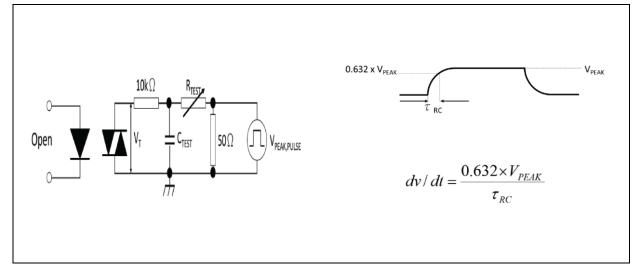


TEST CIRCUIT:



Test Circuit and Waveforms of Turn On Time:

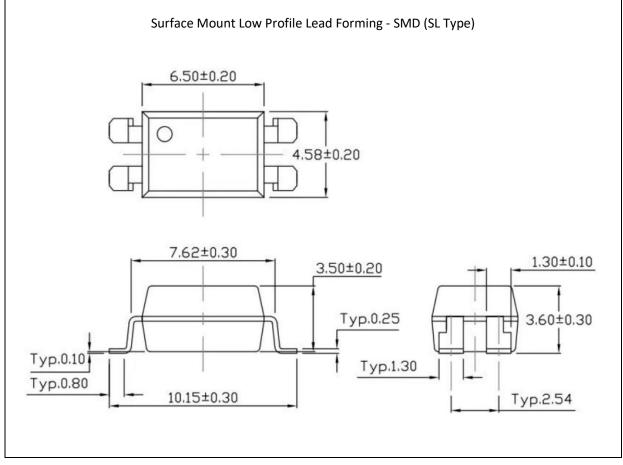
Test Circuit and Waveforms of dV/dt:





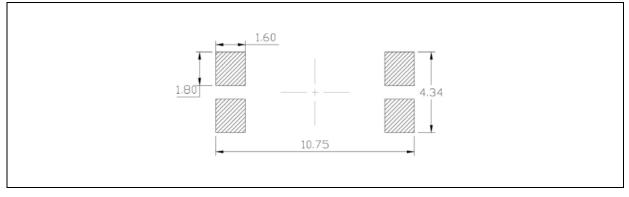
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).

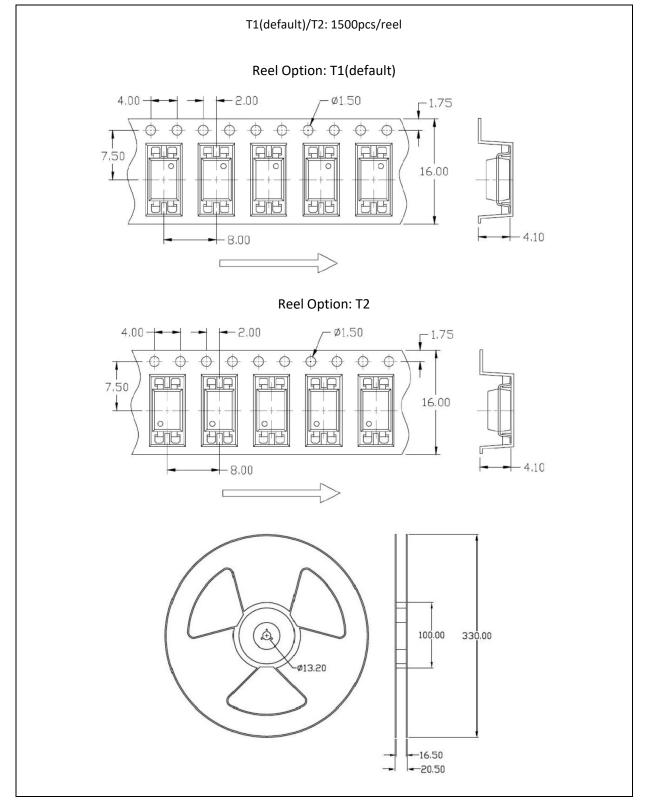
Recommended Soldering Mask:



1. Dimensions are in millimetre (mm).

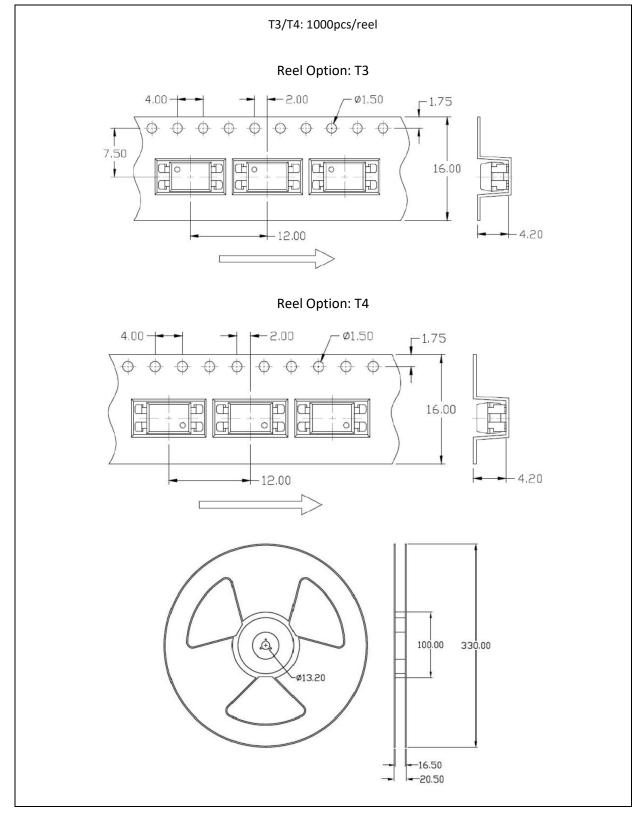


Reel Dimension:





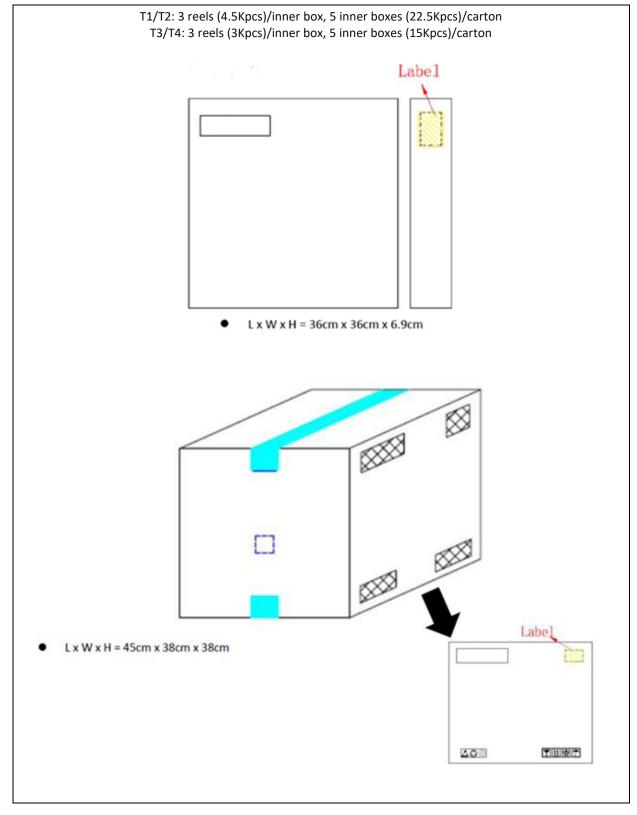
Reel Dimension:





PACKING SPECIFICATION:

Box Dimension:





RECOMMENDED SOLDERING PROFILE:

Reflow Information:

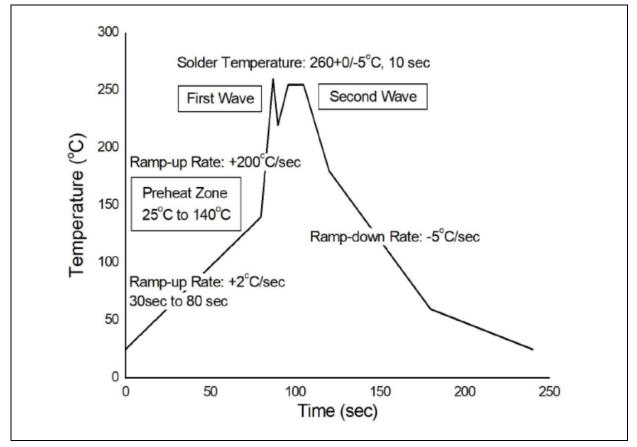
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Supplier $T_p \ge$	T _c T _c T _c -5°C	er $T_p \leq T_c$ User t_p
Tsmax Preheat Are	,	t _p →
← Time 25°C to		+
	Time ⇔	♥ Pb-Free Assembly Profile
Profile Feature		Pb-Free Assembly Profile 150°C
Profile Feature Temperature Min. (T _{smin})	Time → Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Profile Feature	Time → Sn-Pb Assembly Profile 100°C	Pb-Free Assembly Profile 150°C
Profile Feature Temperature Min. (T _{smin}) Temperature Max. (T _{smax})	Time → Sn-Pb Assembly Profile 100°C 150°C	Pb-Free Assembly Profile 150°C 200°C
Profile Feature Temperature Min. (T _{smin}) Temperature Max. (T _{smax}) Time (t _s) from (T _{smin} to T _{smax})	Time → Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds	Pb-Free Assembly Profile 150°C 200°C 60-120 seconds
Profile FeatureTemperature Min. (Tsmin)Temperature Max. (Tsmax)Time (ts) from (Tsmin to Tsmax)Ramp-up Rate (tL to tP)	Time → Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds 3°C/second max.	Pb-Free Assembly Profile 150°C 200°C 60-120 seconds 3°C/second max.
Profile FeatureTemperature Min. (Tsmin)Temperature Max. (Tsmax)Time (ts) from (Tsmin to Tsmax)Ramp-up Rate (tL to tP)Liquidous Temperature (TL)	Time → Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds 3°C/second max. 183°C	Pb-Free Assembly Profile 150°C 200°C 60-120 seconds 3°C/second max. 217°C
Profile FeatureTemperature Min. (Tsmin)Temperature Max. (Tsmax)Time (ts) from (Tsmin to Tsmax)Ramp-up Rate (tL to tP)Liquidous Temperature (TL)Time (tL) Maintained Above (TL)	Time → Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds 3°C/second max. 183°C 60-150 seconds	Pb-Free Assembly Profile 150°C 200°C 60-120 seconds 3°C/second max. 217°C 60-150 seconds
Profile FeatureTemperature Min. (Tsmin)Temperature Max. (Tsmax)Time (ts) from (Tsmin to Tsmax)Ramp-up Rate (tt to tP)Liquidous Temperature (TL)Time (tL) Maintained Above (TL)Peak Body Package Temperature	Time → Sn-Pb Assembly Profile 100°C 150°C 60-120 seconds 3°C/second max. 183°C 60-150 seconds 235°C +0°C / -5°C	Pb-Free Assembly Profile 150°C 200°C 60-120 seconds 3°C/second max. 217°C 60-150 seconds 260°C +0°C / -5°C



RECOMMENDED SOLDERING PROFILE:

Wave Soldering (JESD22-A111 Compliant):



Hand Soldering:

Soldering Temperature	380±5°C
Soldering Time	3 sec max.

Note:

- One time soldering is recommended for all soldering methods.
- Do not solder more than three times for IR reflow soldering.